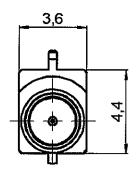
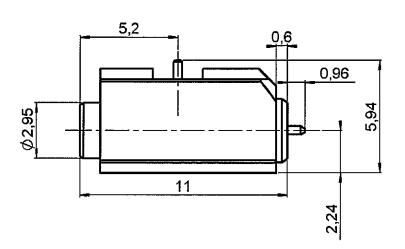
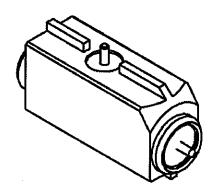
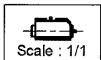
R299.794.880

Series: DIVERS









All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (μm)
BODY	BRASS	GOLD 0.2 OVER NICKEL 2
CENTER CONTACT	BERYLLIUM COPPER	GOLD 0.8 OVER NICKEL 2
OUTER CONTACT	-	_
INSULATOR	POLYETHER ETHERCETONE 30% GF	
GASKET		
OTHERS PARTS	STAINLESS STEEL	
	-	_
	_	_

Issue: 0530 D

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



REEL OF 500 SMT SWITCH RECEPTACLE

EDGE-CARD

R299.794.880

Series : **DIVERS**

PACKAGING

Standard	Unit	Other
500	'W' option	Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

Impedance

50 Ω 0-3 GHz

Frequency VSWR

1.4* + 0.000

0.000 x F(GHz) Maxi

Insertion loss

- (

0.3** √F(GHz) dB Maxi - F(GHz)) dB Maxi

RF leakage - (
Voltage rating

Dielectric withstanding voltage

Insulation resistance

100 Veff Maxi250 Veff mini5000 MΩ mini

ENVIRONMENTAL

Operating temperature

-40/+110 ° C

Hermetic seal Panel leakage NA Atm.cm3/s

NA

OTHER CHARACTERISTICS

Assembly instruction

Others:

* 1.4 Max at 2.5 GHz

**isol between 2 ways:-22dBmin at 2.5GHz

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end Axial force – Opposite end

Torque

N mini N mini

N.cm mini

Recommended torque

Mating

NA N.cm

Panel nut

NA N.cm

Mating life

5000 Cycles mini

Weight

1.002 g

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R299.794.880

Series: **DIVERS**

SOLDER PROCEDURE

1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.

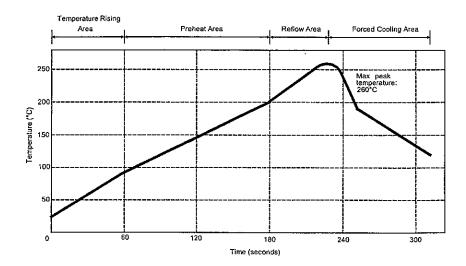
We advise a thickness of 150 microns mini (0.006 inch mini). Verify that the edges of the zone are clean.

2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.

Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.

- 3. Soldering by infra-red reflow. Below, please find the typical profile to use.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 -4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

Issue: 0530 D

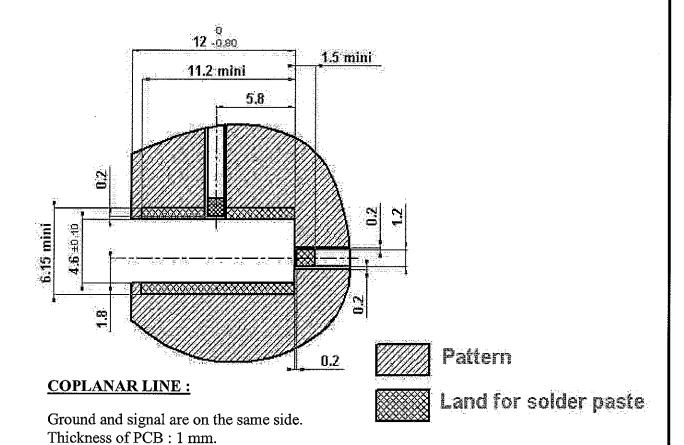
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Series: DIVERS

INFORMATIONS



Issue: 0530 D

of the PCB.

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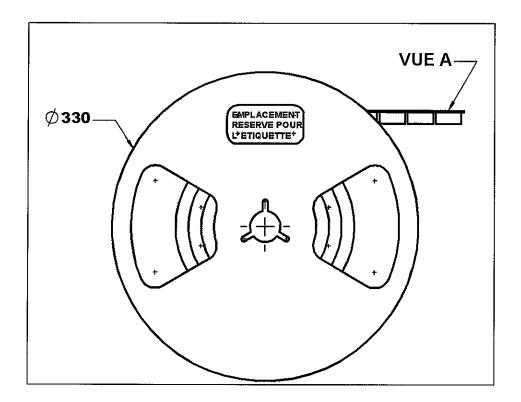
The material of PCB is glass – epoxy composite (Er=4.8) The solder resist should be printed except for the land pattern



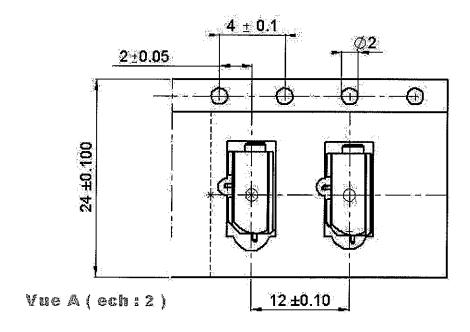
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Series: DIVERS

PACKAGING



bobine Ech: 0.7



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